

No.	Ref.	Qty	Value	Part Number	Manufacturer	Description	Packaging	Typical Dimensions in mm (inches)
1	IC1	1	-	TPD4207F	TOSHIBA	IPD 600V	SSOP30	20.0 x 14.2
2	IC5	1	-	TMPM4K0FSADUG	TOSHIBA	TXZ4 Microcomputer	LQFP32	7.0 x 7.0
3	Q1, Q2	2	-	SSM3K16CTC	TOSHIBA	Small-signal MOSFET	CST3C	0.8 x 0.6
4	D1	1	-	CUHS10F60	TOSHIBA	Schottky barrier diode	US2H	2.5 x 1.4
5	DS1, DS2	2	-	TLP2362	TOSHIBA	Photocoupler (IC output)	SO6	3.7 x 7.0
6	X1	1	10MHz	FCX-04C	River Eletec	X'tal oscillator	-	3.2 x 2.5
7	R1, R13	2	10kΩ	-	-	Carbon, ±5%	-	1.0 x 0.5 (0402)
8	R2, R6	2	150Ω	-	-	Carbon, ±1%	-	1.0 x 0.5 (0402)
9	R3	1	100Ω	-	-	Carbon, ±1%	-	1.0 x 0.5 (0402)
10	R4	1	11kΩ	-	-	Carbon, ±1%	-	1.0 x 0.5 (0402)
11	R5	1	3.6kΩ	-	-	Carbon, ±1%	-	1.0 x 0.5 (0402)
12	R7, R8	2	240mΩ	SL1TTER240F	KOA	Current detecting resistor, 1W, ±1%	-	6.3 x 3.2 (2512)
13	R9, R10, R11	3	180kΩ	-	-	Carbon, ±1%	-	1.6 x 0.8 (0603)
14	R12	1	3.3kΩ	-	-	Carbon, ±1%	-	1.6 x 0.8 (0603)
15	R14, R15, R17, R18	4	180Ω	-	-	Carbon, ±1%	-	1.0 x 0.5 (0402)
16	R16, R19	2	2.7kΩ	-	-	Carbon, ±5%	-	1.0 x 0.5 (0402)
17	R20, R21, R22, R23, R24, R25, R26, R27	8	100Ω	-	-	Carbon, ±5%	-	1.0 x 0.5 (0402)
18	C1, C2, C3	3	4.7μF	-	-	Ceramic, 25V, ±10%	-	2.0 x 1.2 (0805)
19	C6, C7, C9	3	2.2μF	-	-	Ceramic, 25V, ±10%	-	2.0 x 1.2 (0805)
20	C4, C5	2	10nF	-	-	Ceramic, 25V, ±10%	-	3.2 x 1.6 (1206)
21	C8, C10	2	1μF	-	-	Polypropylene Film, 650V, ±10 %	DIP	-
22	C11	1	1nF	-	-	Polypropylene Film, 650V, ±10 %	DIP	-
23	C12, C14	2	2.2μF	-	-	Ceramic, 10V, ±10%	-	1.0 x 0.5 (0402)
24	C13, C17	2	100nF	-	-	Ceramic, 25V, ±10%	-	1.0 x 0.5 (0402)
25	C15, C16	2	4.7μF	-	-	Ceramic, 10V, ±10%	-	1.0 x 0.5 (0402)
26	C18, C19	2	5pF	-	-	Ceramic, 50V, ±5%	-	1.0 x 0.5 (0402)

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